

CH03-BG - SIM CARD HOLDER 6 OR 8 PINS

FEATURES

- 1. GENERAL CHARACTERISTICS
 DIMENSIONS: 29.65L x 17.20W x 2.20H mm
 WEIGHT: APPROX. 0.85g
 CONTACT PRINCIPLE: FRICTION TECHNOLOGY
 OPERATING POSITION: SHAFT UP / DOWN / HORIZONTAL
 MOUNTING SYSTEM: SMT TYPE
 DURABILITY: 10,000 CYCLES MIN.

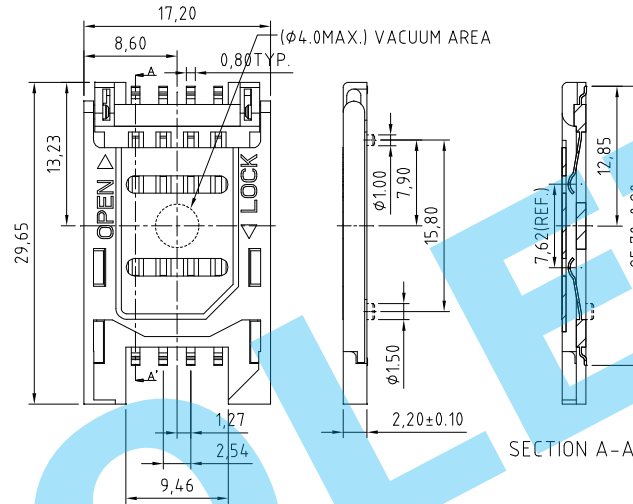
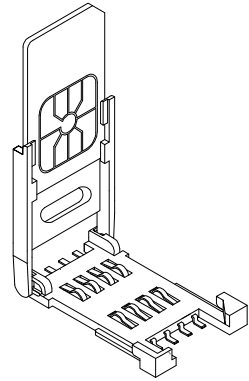
- 2. MECHANICAL CHARACTERISTICS
 INSULATION MATERIAL: THERMOPLASTIC, UL 94 V-0

- 3. ELECTRICAL CHARACTERISTICS
 NUMBER OF CONTACTS (OPTIONAL): 6, 8 PINS
 CONTACT RESISTANCE: 50M OHMS TYP. 100M OHMS MAX.
 INSULATION RESISTANCE: > 1000M OHMS / 500V DC

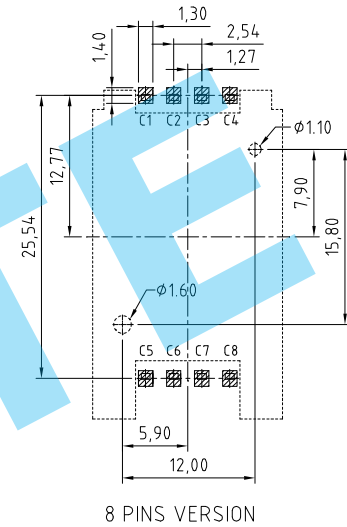
- 4. SOLDERABILITY
 WAVE: NOT APPLICABLE
 VAPORPHASE: 215°C, 30 SEC. MAX.
 IR REFLOW: 260°C, 10 SEC. MAX.
 MANUAL SOLDERING: 360°C, 3 SEC. MAX.

- 5. ENVIRONMENTAL CHARACTERISTICS
 OPERATING TEMPERATURE: -40°C ~ +85°C
 OPERATING HUMIDITY: 10% ~ 95% RH
 STORAGE TEMPERATURE: -40°C ~ +85°C
 STORAGE HUMIDITY: 10% ~ 95% RH
 THERMAL SHOCK -40°C ~ +85°C, 5 CYCLES
 DAMP HEAT: 40°C, 90% RH, 500 HR
 SALT MIST: 35°C, 5%, NaCl, 48 HR

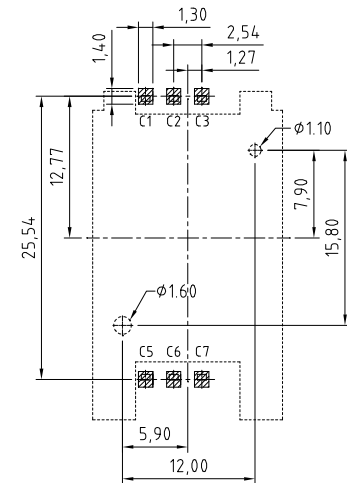
- NOTES:
- 1. ACCEPTABLE SIM CARD SIZE SHOULD MEET GSM 11.11 SPECIFICATION REQUIREMENT.



SECTION A-A'



8 PINS VERSION



6 PINS VERSION

RECOMMENDED PCB LAYOUT

HOW TO ORDER



NO. OF CONTACTS
06 OR 08

WITH OR WITHOUT
LOCATING PEG
A = WITH
B = WITHOUT

PACKAGING OPTIONS
R = REEL
(600PCS/REEL)

REV. DATE & DRN	1.0 01/10/10L - NYW RELEASE
	1.1 28/07/05 - NYW AMEND PACK OPTION.
	1.2 28/05/07 - NYW ADD NOTES 1.
	1.3 28/09/07 - NYW REMOVE PACK OPTION TUBE.
	1.4 27/11/07 - NYW ADD SEPARATE PCB LAYOUT.
	1.5 28/04/09 - PN PACKAGING DRAWING ADDED
	1.6 01/06/11 - NYW COVER MODIFICATION.

Scale: 2:1	THIRD ANGLE	Unstated Tolerances: 0 Dec Places 1 Dec Places 2 Dec Places 3 Dec Places	Material SEE NOTE
Drawn: NYW			NOT TO SCALE
App'd: XXXX	Title: SIM CARD ACCEPTOR		Unit: mm
Date: 01 JUN '11	Revision: 1.6		

www.gradconn.com

THIS DRAWING IS CONFIDENTIAL AND MUST NOT BE COPIED OR DISCLOSED WITHOUT WRITTEN CONSENT

Type: CH03-BG
CH03-BG
Drawing Number:
Sheet 1 of 2
Drawing © E and O E